

Symbol	Characteristic / Test Conditions	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			0.43	°C/W
W_T	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb-in
				1.1	N·m

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

TYPICAL PERFORMANCE CURVES

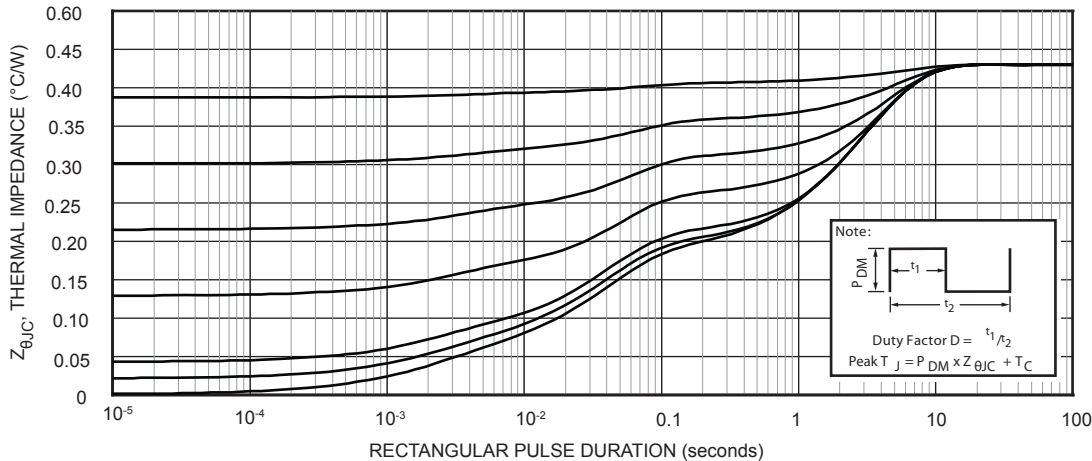


FIGURE 1. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

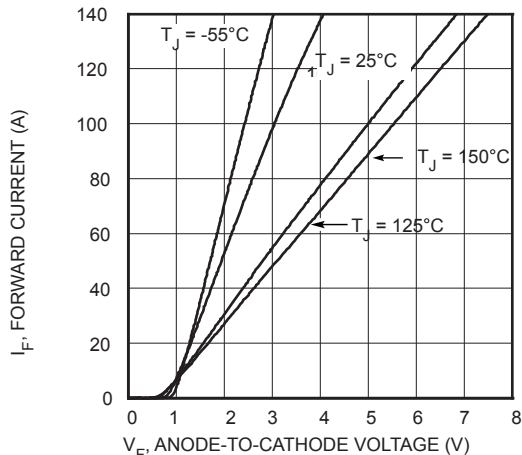


FIGURE 2. Forward Current vs. Forward Voltage

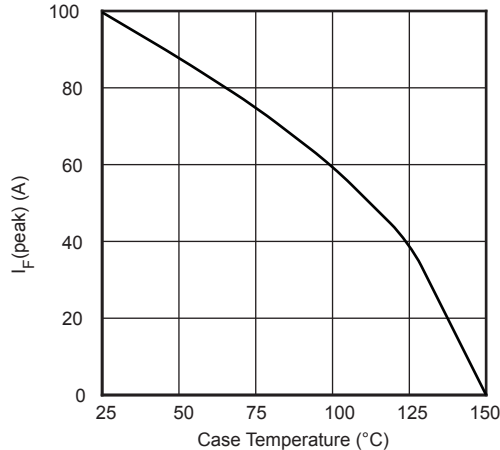


FIGURE 3. Maximum Forward Current vs. Case Temperature

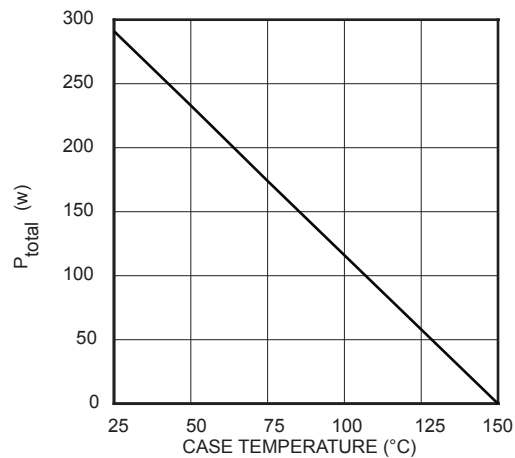


Figure 4. Maximum Power Dissipation vs. Case Temperature

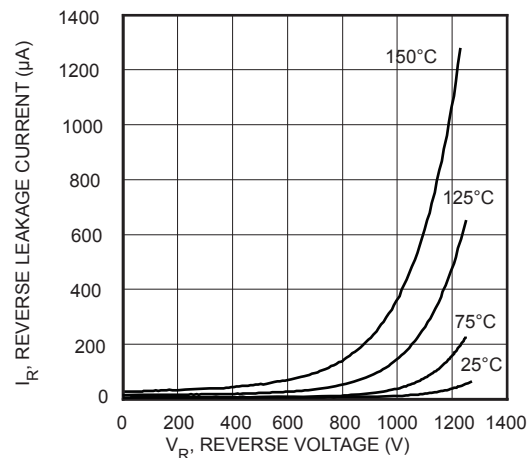


Figure 5. Reverse Leakage Currents vs. Reverse Voltage

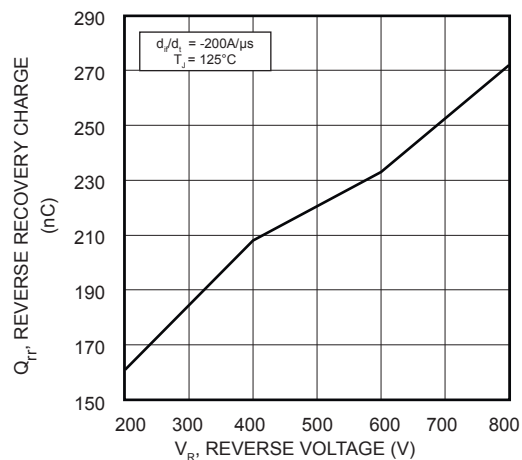
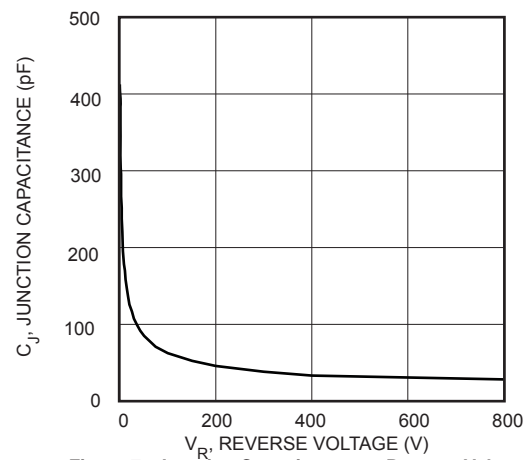
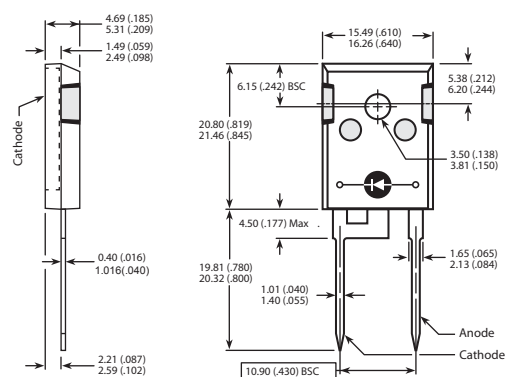
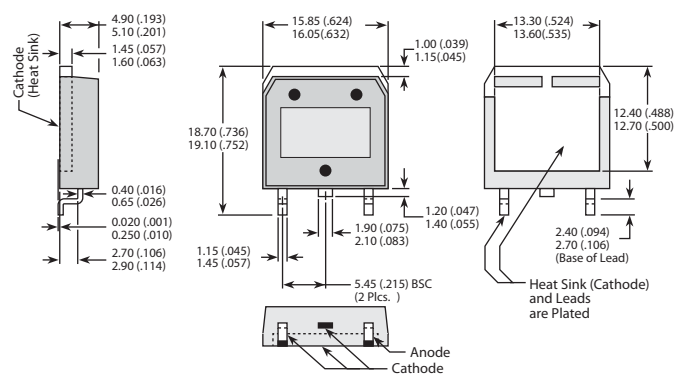
Figure 6. Reverse Recovery Charge vs. V_R 

Figure 7. Junction Capacitance vs. Reverse Voltage

TO-247 Package Outline



Dimensions in Millimeters and (Inches)

D³PAK Package Outline

Dimensions in Millimeters and (Inches)

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